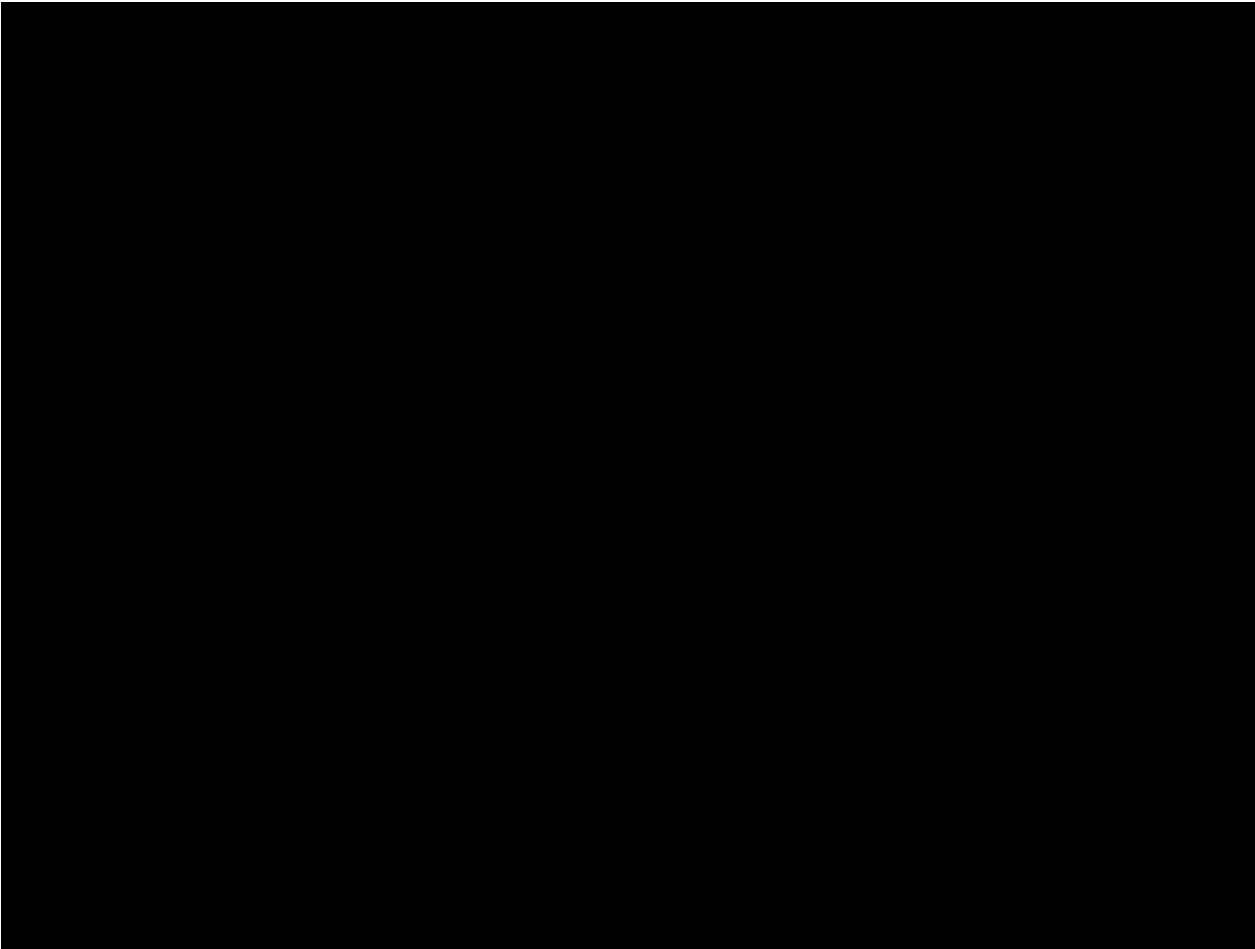
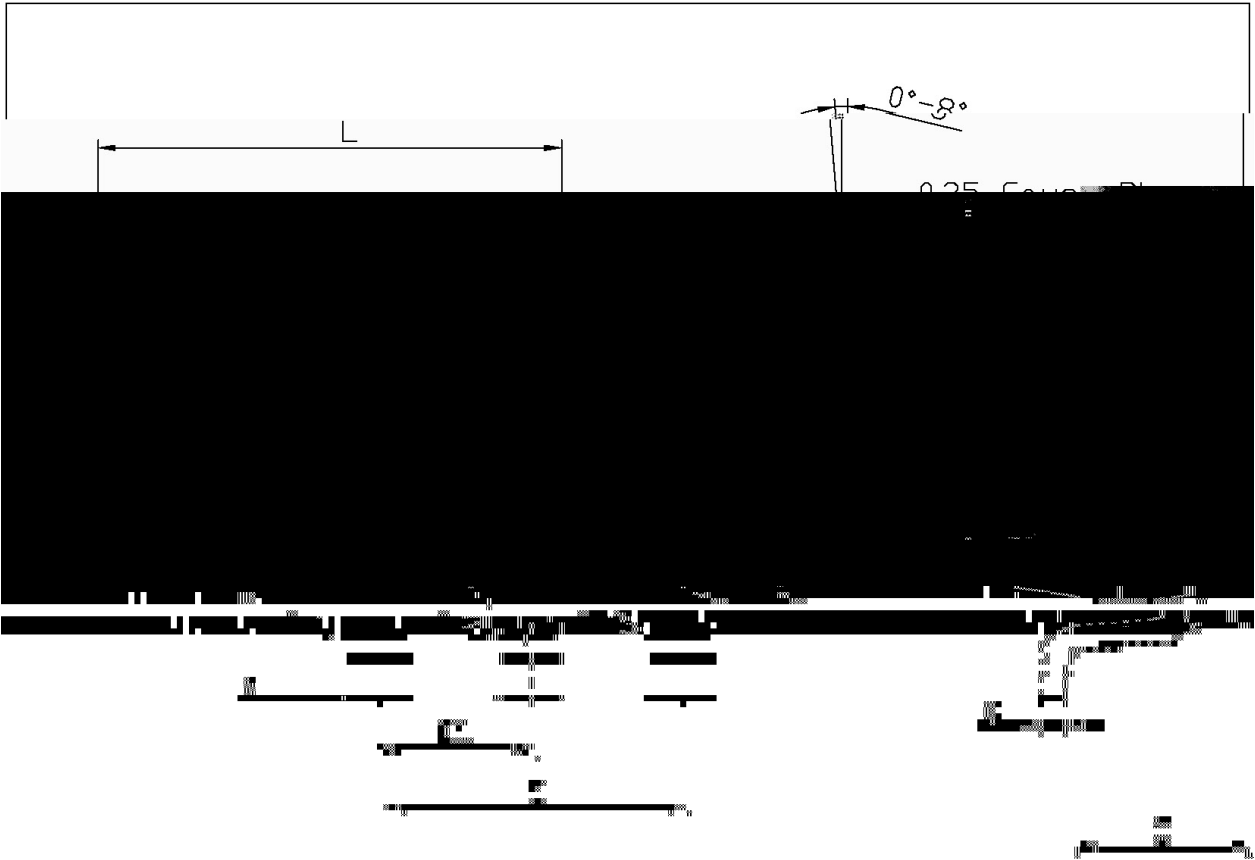


ᵛ "ᱚ	ᵛ N	"ᱚ ᱚ	D ᱚ
ᱚ ᱚ ᱚ ᱚ ᱚ ᱚ	V _{IN_MAX}	30	V
ᱚ ᱚ ᱚ ᱚ ᱚ ᱚ	V _{IN}	-0.3~30	V
CE ᱚ ᱚ ᱚ ᱚ	V _{CE}	V _{IN} -0.3~V _{IN} +0.3	V
ᱚ, ᱚ ᱚ	I _{OUT}	0~500	mA
ᱚ "ᱚ ᱚ	P _D	0.3	W

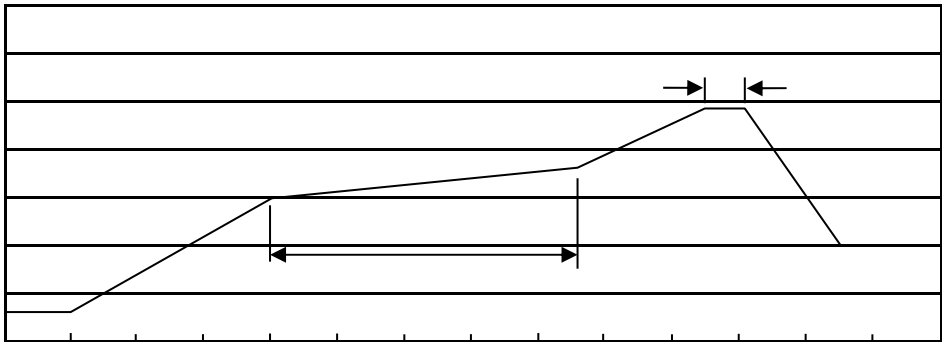
/ Functionl Block Diagram



/ Package Dimensions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



б " χ

1. 150~180 ℃, Time: 60~90sec;
2. 245±5 ℃, Duration: 5~0.5sec;
3. Cooling Speed: 2~10 ℃/sec.

Note:

1. Preheating: 150~180 ℃, Time: 60~90sec.
2. Peak Temp.: 245±5 ℃, Duration: 5~0.5sec.
3. Cooling Speed: 2~10 ℃/sec.

/ Resistance to Soldering Heat Test Conditions

260±5 ℃, Time: 10±1 sec. Temp.: 260±5 Time: 10±1 sec

/ Packaging SPEC.

REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT23-5/6	3,000	10	30,000	4	120,000	7 × 8	210×205×205	445×435×230

/ Notices

All information provided in this document is subject to legal disclaimers.